

PROCEEDINGS OF SPIE

***Laser Applications in  
Microelectronic and  
Optoelectronic Manufacturing  
(LAMOM) XXIII***

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**29–31 January 2018  
San Francisco, California, United States**

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Okamoto Optics Works (Japan)  
Plymouth Grating Laboratory (United States)

*Published by*  
SPIE

**Volume 10519**

Proceedings of SPIE 0277-786X, V. 10519

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Please use the following format to cite material from these proceedings:

Author(s), "Title of Paper," in *Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XXIII*, edited by Beat Neuenschwander, Costas P. Grigoropoulos, Tetsuya Makimura, Gediminas Račiukaitis, Proceedings of SPIE Vol. 10519 (SPIE, Bellingham, WA, 2018) Seven-digit Article CID Number.

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781510615236

ISBN: 9781510615243 (electronic)

Published by

**SPIE**

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

[SPIE.org](http://SPIE.org)

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